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Should be replaced with:

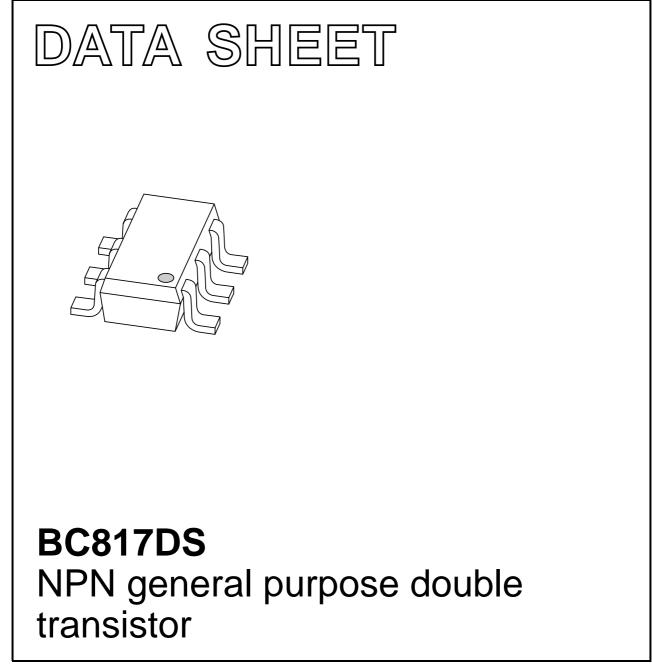
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Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2002 Aug 09 2002 Nov 22



## **BC817DS**

#### FEATURES

- High current (500 mA)
- 600 mW total power dissipation
- Replaces two SOT23 packaged transistors on same PCB area.

#### APPLICATIONS

- · General purpose switching and amplification
- Push-pull amplifiers
- Multi-phase stepper motor drivers.

#### DESCRIPTION

NPN transistor pair in a SOT457 (SC-74) plastic package.

#### MARKING

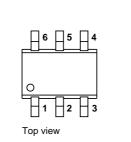
TYPE NUMBER	MARKING CODE
BC817DS	N3

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	45	V
I <sub>C</sub>	collector current (DC)	500	mA
I <sub>CM</sub>	peak collector current	1	А

#### PINNING

PIN	DESCRIPTION	
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
6, 3	collector	TR1; TR2



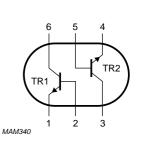


Fig.1 Simplified outline (SOT457) and symbol.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per transistor unless otherwise specified					
collector-base voltage	open emitter	-	50	V	
collector-emitter voltage	open base	-	45	V	
emitter-base voltage	open collector	-	5	V	
collector current (DC)		_	500	mA	
peak collector current		_	1	А	
peak base current		-	200	mA	
total power dissipation	$T_{amb} \le 25 \ ^{\circ}C; \text{ note } 1$	-	370	mW	
storage temperature		-65	+150	°C	
junction temperature		_	150	°C	
operating ambient temperature		-65	+150	°C	
e			•	<u>.</u>	
total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1	-	600	mW	
	collector-base voltagecollector-emitter voltageemitter-base voltagecollector current (DC)peak collector currentpeak base currenttotal power dissipationstorage temperaturejunction temperatureoperating ambient temperature	collector-base voltageopen emittercollector-emitter voltageopen baseemitter-base voltageopen collectorcollector current (DC)peak collector currentpeak base currenttotal power dissipation $T_{amb} \leq 25 \ ^{\circ}C$ ; note 1storage temperaturejunction temperatureoperating ambient temperature	collector-base voltageopen emitter-collector-emitter voltageopen base-emitter-base voltageopen collector-collector current (DC)-peak collector current-peak base current-total power dissipation $T_{amb} \le 25$ °C; note 1storage temperature-junction temperature-operating ambient temperature-65	collector-base voltageopen emitter-50collector-emitter voltageopen base-45emitter-base voltageopen collector-5collector current (DC)-500peak collector current-1peak base current-200total power dissipation $T_{amb} \le 25$ °C; note 1-370storage temperature65+150junction temperature-150operating ambient temperature-65+150	

#### Note

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	208	K/W

#### Note

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

#### CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

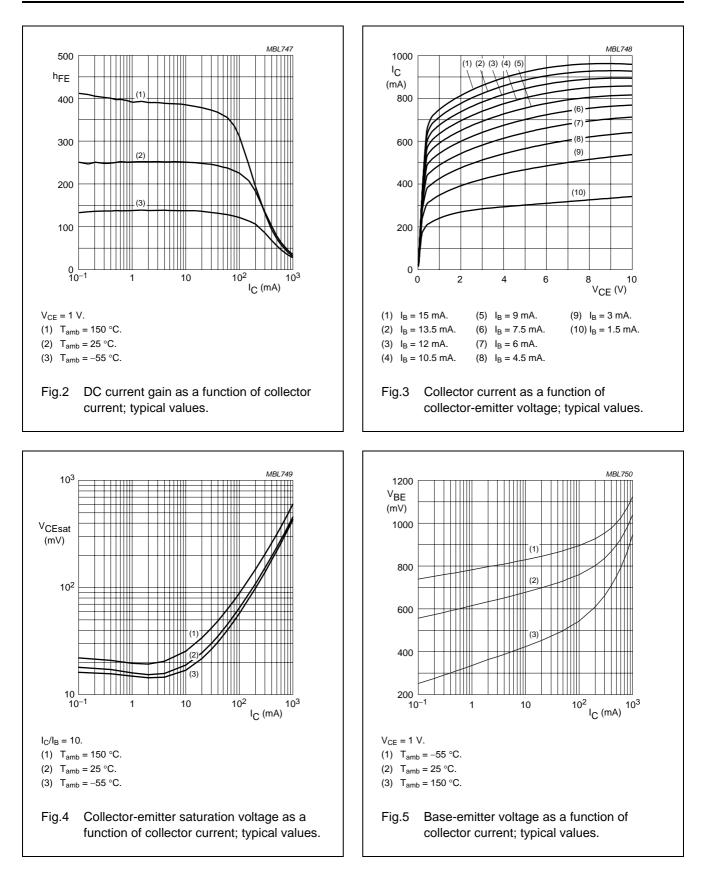
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transi	Per transistor					
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 20 \text{ V}; I_E = 0$	-	_	100	nA
		$V_{CB} = 20 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	-	-	5	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0$	-	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 1 V; I <sub>C</sub> = 100 mA; note 1	160	-	400	
		V <sub>CE</sub> = 1 V; I <sub>C</sub> = 500 mA; note 1	40	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA; note 1	-	-	700	mV
V <sub>BE</sub>	base-emitter voltage	$V_{CE} = 1 V; I_C = 500 mA;$ notes 1 and 2	-	-	1.2	V
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = 10 V; I <sub>E</sub> = I <sub>e</sub> = 0; f = 1 MHz	-	5	_	pF
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 10 mA; f = 100 MHz	100	-	-	MHz

#### Notes

1. Pulse test:  $t_p \leq 300~\mu\text{s};~\delta \leq 0.02.$ 

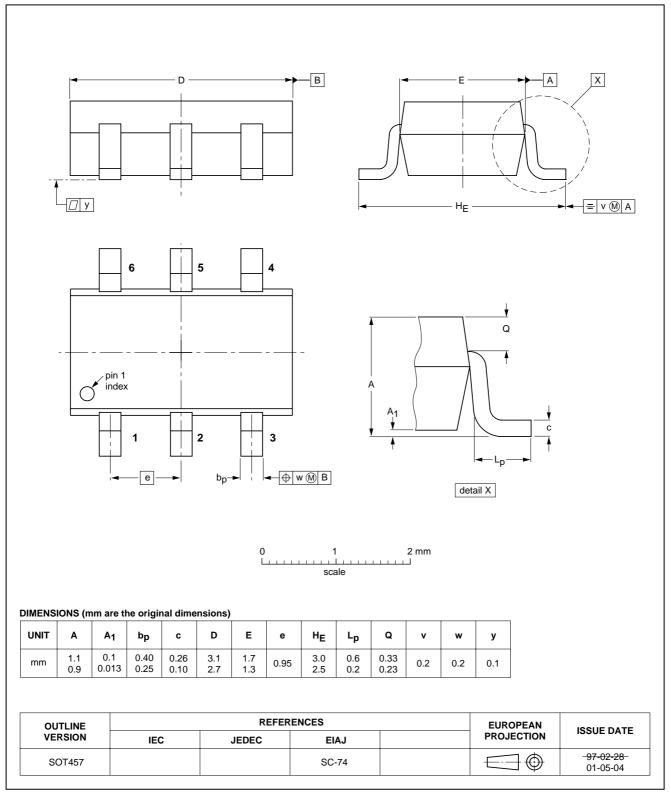
2.  $V_{BE}$  decreases by approximately -2 mV/K with increasing temperature.

## BC817DS



#### PACKAGE OUTLINE

#### Plastic surface mounted package; 6 leads



## BC817DS

SOT457

BC817DS

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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